

**THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: Yoshihisa MATSUBARA, et al.  
Filed: **Concurrently herewith**  
For: METHOD FOR MANUFACTURING SEMICONDCUTOR....  
Serial No.: **Concurrently herewith**

April 23, 2001

Assistant Commissioner of Patents  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

S I R:

Prior to the issuance of an Office Action, please amend the application as follows:

**IN THE CLAIMS**

A<sup>1</sup>  
3. (Amended) A method according to claim 1, wherein said processing step is a cleaning step performed during, before and after a step that includes chemical mechanical polishing (CMP) for forming said wiring.

Please add the following new claim

A<sup>2</sup>  
12. (New) A method according to claim 2, wherein said processing step is a cleaning step performed during, before and after a step that includes chemical mechanical polishing (CMP) for forming said wiring.